

**N and P- Channel 30-V (D-S) MOSFET**
**GENERAL DESCRIPTION**

The ME4542 is the N and P Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

**FEATURES**

- $R_{DS(ON)} \leq 25m\Omega @ V_{GS}=10V$  (N-Ch)
- $R_{DS(ON)} \leq 40m\Omega @ V_{GS}=4.5V$  (N-Ch)
- $R_{DS(ON)} \leq 35m\Omega @ V_{GS}=-10V$  (P-Ch)
- $R_{DS(ON)} \leq 58m\Omega @ V_{GS}=-4.5V$  (P-Ch)
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

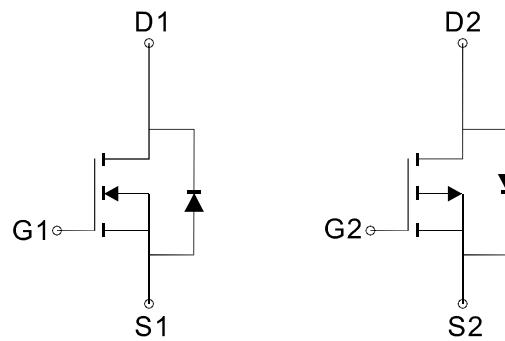
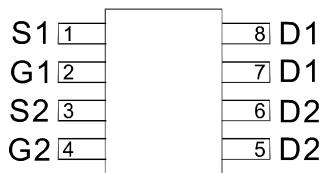
**APPLICATIONS**

- Power Management
- DC/DC Converter
- LCD TV & Monitor Display inverter
- CCFL inverter
- LCD Display inverter

**PIN CONFIGURATION**

(SOP-8)

Top View



Ordering Information: ME4542 (Pb-free)

N-Channel MOSFET    P-Channel MOSFET

ME4542-G (Green product-Halogen free)

**Absolute Maximum Ratings ( $T_A=25^\circ C$  Unless Otherwise Noted)**

| Parameter                                | Symbol          | N-Channel       | P-Channel       | Unit         |
|--|-----------------|-----------------|-----------------|--------------|
|  |                 | Maximum Ratings | Maximum Ratings |              |
| Drain-Source Voltage                     | $V_{DS}$        | 30              | -30             | V            |
| Gate-Source Voltage                      | $V_{GS}$        | $\pm 20$        | $\pm 20$        |              |
| Continuous Drain Current                 | $I_D$           | 7.1             | -6              | A            |
|  |                 | 5.7             | -4.8            |              |
| Pulsed Drain Current                     | $I_{DM}$        | 28              | -24             | W            |
| Maximum Power Dissipation                | $P_D$           | 2               | 2               |              |
|  |                 | 1.3             | 1.3             |              |
| Operating Junction Temperature           | $T_J$           | -55 to 150      |                 |              |
| Thermal Resistance-Junction to Ambient * | $R_{\theta JA}$ | 62.5            | 62.5            | $^\circ C/W$ |

\*The device mounted on 1in2 FR4 board with 2 oz copper

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**Electrical Characteristics (TA = 25°C Unless Otherwise Specified)**

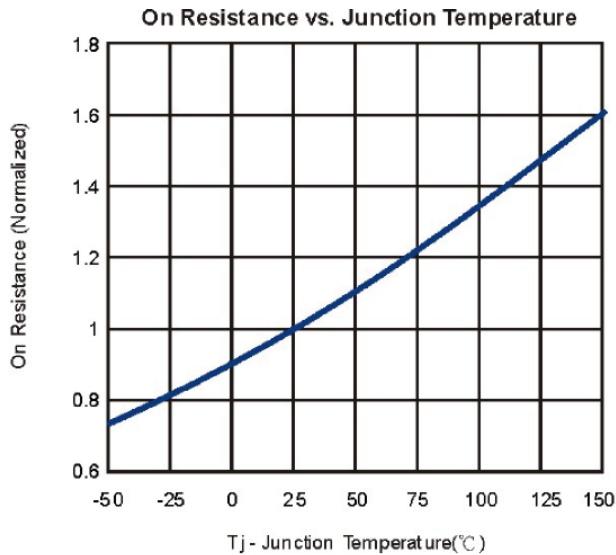
| <b>Symbol</b>       | <b>Parameter</b>                              | <b>Conditions</b>   | <b>Min</b>   | <b>Typ</b>  | <b>Max</b>   | <b>Unit</b> |
|---------------------|---|---|--------------|-------------|--------------|-------------|
| <b>STATIC</b>       |   |   |              |             |              |             |
| V(BR)DSS            | Drain-Source Breakdown Voltage                | V <sub>GS</sub> =0V, I <sub>D</sub> =250 μA<br>V <sub>GS</sub> =0V, I <sub>D</sub> =-250 μA   | N-Ch<br>P-Ch | 30<br>-30   |              | V           |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                        | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA<br>V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250 μA   | N-Ch<br>P-Ch | 1.0<br>-1.0 |              | V           |
| I <sub>GSS</sub>    | Gate Leakage Current                          | V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V  | N-Ch<br>P-Ch |             | ±100<br>±100 | nA          |
| I <sub>DSs</sub>    | Zero Gate Voltage Drain Current               | V <sub>DS</sub> =30V, V <sub>GS</sub> =0V<br>V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V   | N-Ch<br>P-Ch |             | 1<br>-1      | μA          |
| R <sub>DS(ON)</sub> | Drain-Source On-State Resistance <sup>a</sup> | V <sub>GS</sub> =10V, I <sub>D</sub> = 6.7A<br>V <sub>GS</sub> =-10V, I <sub>D</sub> = -6.1A  | N-Ch<br>P-Ch | 21<br>30    | 25<br>35     | mΩ          |
|                     |   | V <sub>GS</sub> =4.5V, I <sub>D</sub> = 5.0A<br>V <sub>GS</sub> =-4.5V, I <sub>D</sub> = -5.0A  | N-Ch<br>P-Ch | 32<br>48    | 40<br>58     |             |
| V <sub>SD</sub>     | Diode Forward Voltage                         | I <sub>S</sub> =1.7A, V <sub>GS</sub> =0V<br>I <sub>S</sub> =-1.7A, V <sub>GS</sub> =0V   | N-Ch<br>P-Ch | 0.8<br>-0.8 | 1.2<br>-1.2  | V           |
| <b>DYNAMIC</b>      |   |   |              |             |              |             |
| Q <sub>g</sub>      | Total Gate Charge                             | N-Channel<br>V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>D</sub> =6.7A<br>P-Channel<br>V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-6.1A | N-Ch<br>P-Ch | 12<br>21    |              | nC          |
| Q <sub>gs</sub>     | Gate-Source Charge                            |   | N-Ch<br>P-Ch | 2<br>4      |              |             |
| Q <sub>gd</sub>     | Gate-Drain Charge                             |   | N-Ch<br>P-Ch | 2.5<br>6    |              |             |
| C <sub>iss</sub>    | Input Capacitance                             | N-Channel<br>V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz<br>P-Channel<br>V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz                                  | N-Ch<br>P-Ch | 360<br>840  |              | pF          |
| C <sub>oss</sub>    | Output Capacitance                            |   | N-Ch<br>P-Ch | 70<br>120   |              |             |
| C <sub>rss</sub>    | Reverse Transfer Capacitance                  |   | N-Ch<br>P-Ch | 17<br>32    |              |             |
| R <sub>g</sub>      | Gate Resistance                               | V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz  | N-Ch<br>P-Ch | 0.5<br>5.5  |              | Ω           |
| t <sub>d(on)</sub>  | Turn-On Delay Time                            | N-Channel<br>V <sub>DD</sub> =15V, R <sub>L</sub> =15Ω<br>I <sub>D</sub> =1A, V <sub>GEN</sub> =10V, R <sub>G</sub> =6Ω   | N-Ch<br>P-Ch | 9.3<br>32   |              | ns          |
| t <sub>r</sub>      | Turn-On Rise Time                             |   | N-Ch<br>P-Ch | 14<br>13    |              |             |
| t <sub>d(off)</sub> | Turn-Off Delay Time                           |   | N-Ch<br>P-Ch | 32<br>58    |              |             |
| t <sub>f</sub>      | Turn-Off Fall Time                            |   | N-Ch<br>P-Ch | 3.2<br>6.8  |              |             |

Notes: a. Pulse test; pulse width ≤ 300us, duty cycle≤ 2%

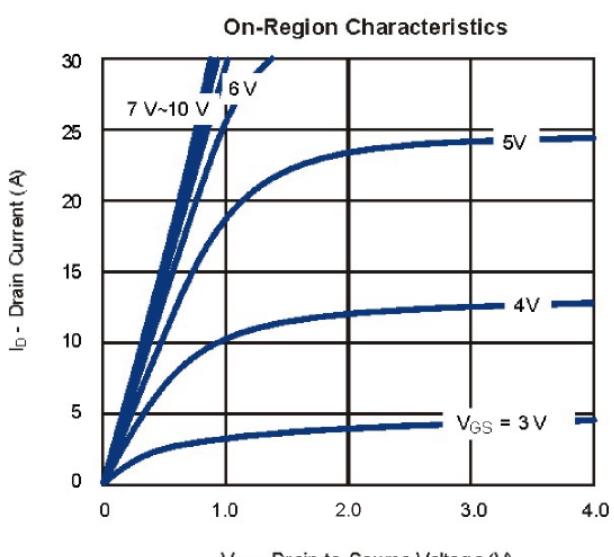
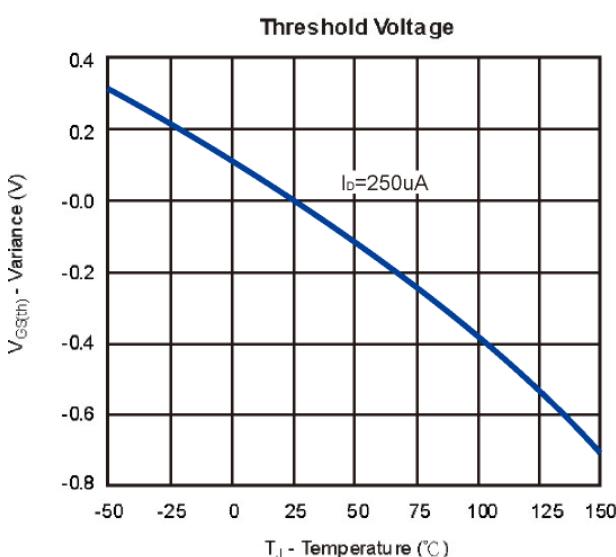
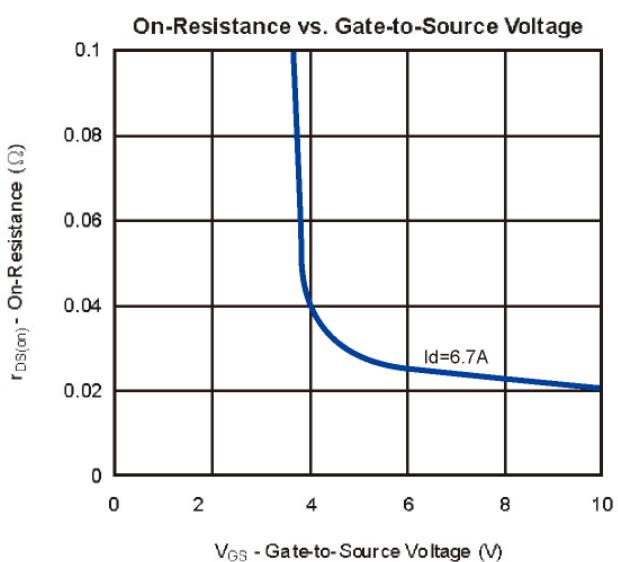
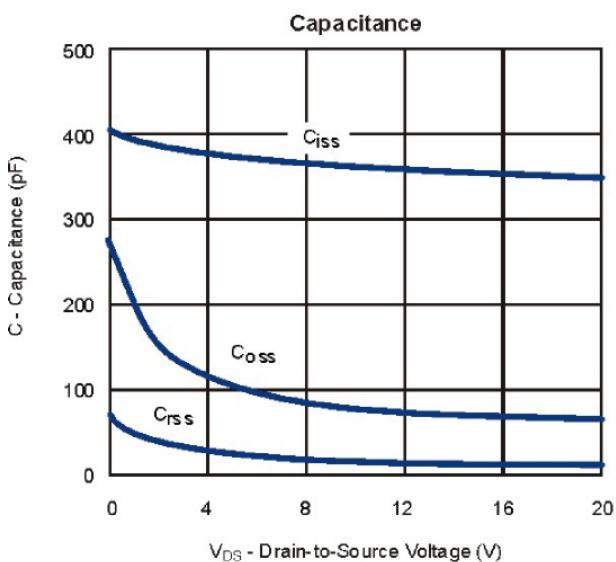
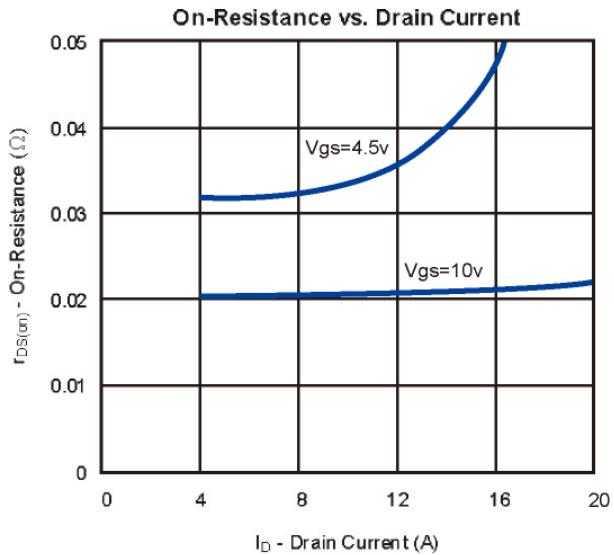
b. Matsuki Electric/ Force mos reserves the right to improve product design, functions and reliability without notice.

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**Typical Characteristics (T<sub>J</sub> =25°C Noted)**



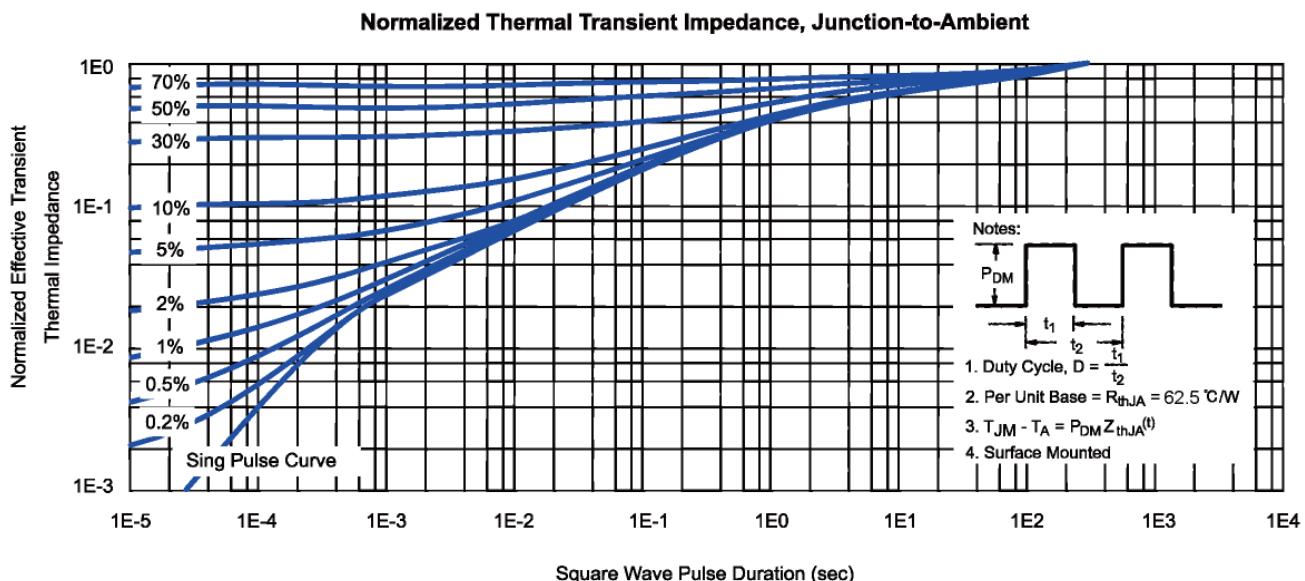
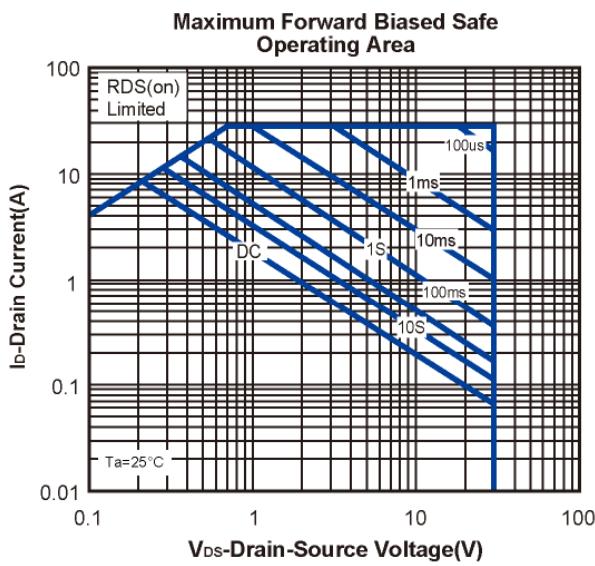
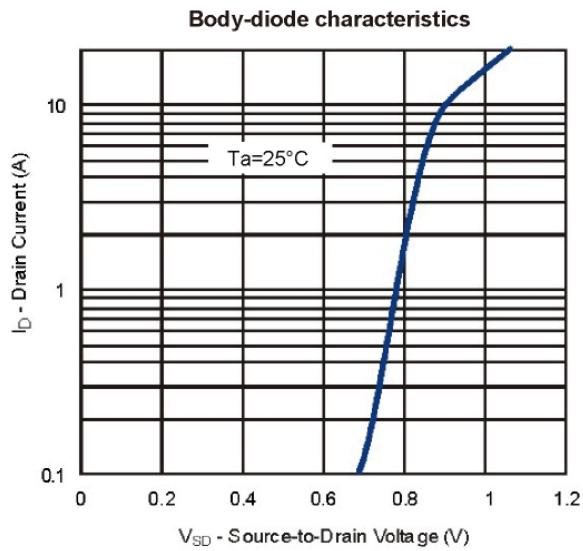
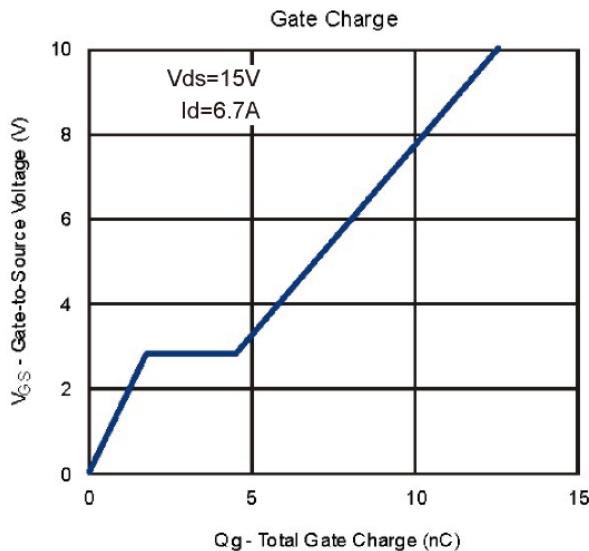
**N-CHANNEL**



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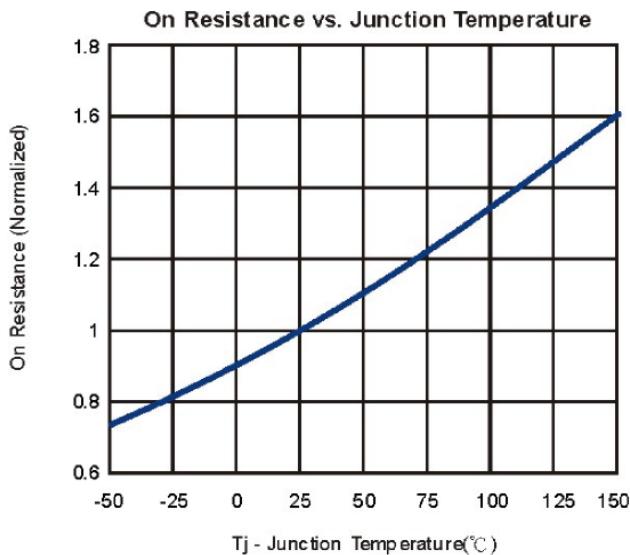
**Typical Characteristics (T<sub>J</sub> =25°C Noted)**

**N-CHANNEL**

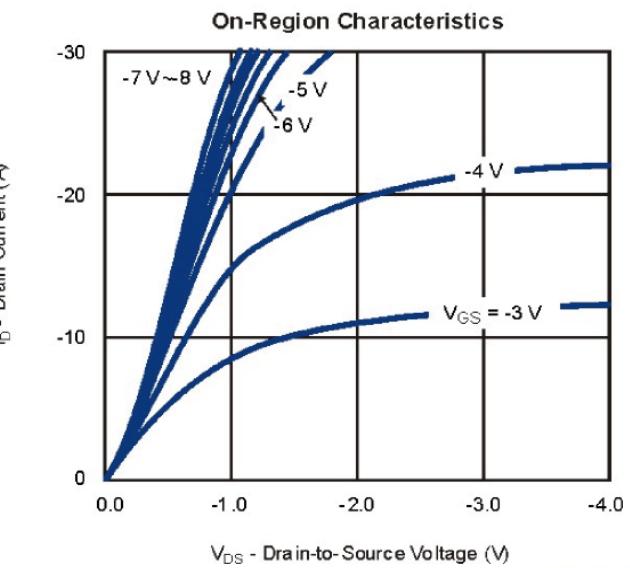
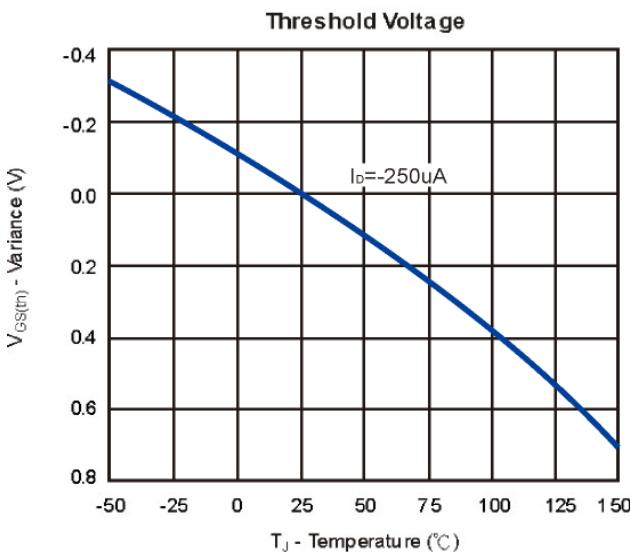
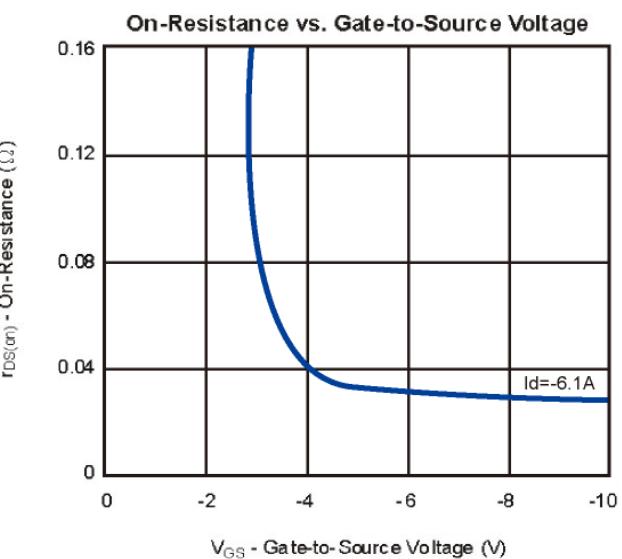
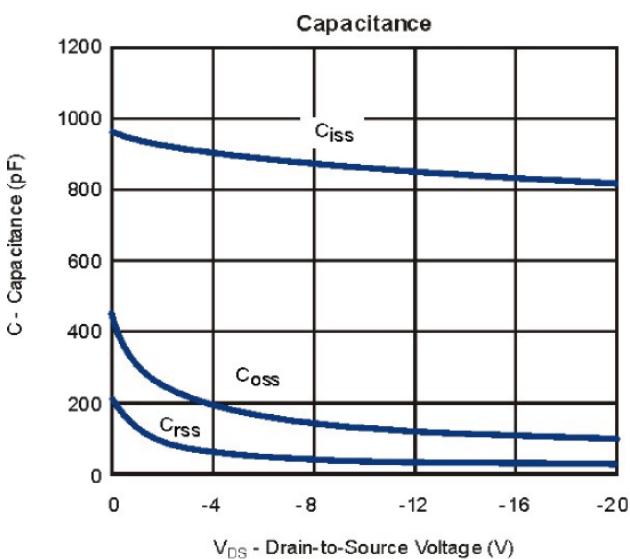
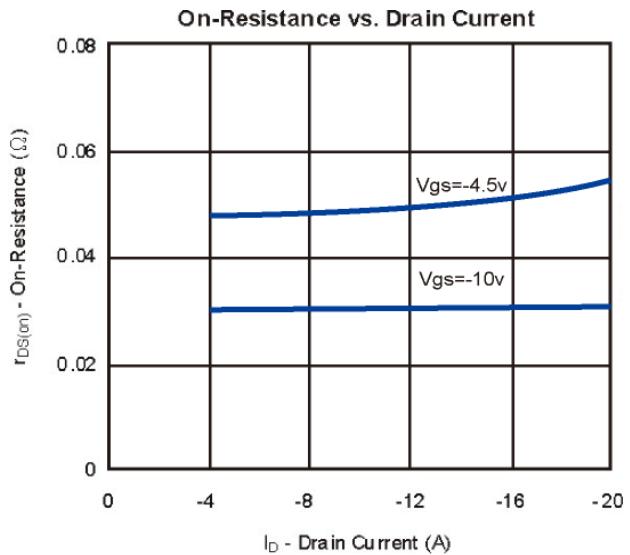


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**Typical Characteristics (T<sub>J</sub> =25°C Noted)**



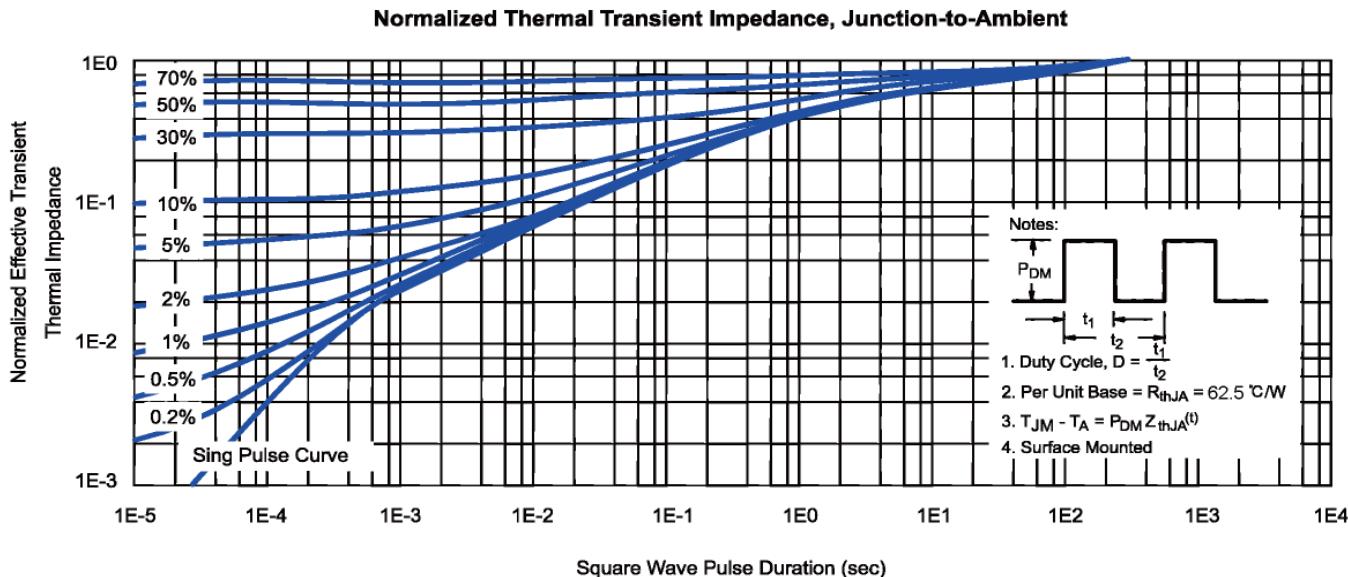
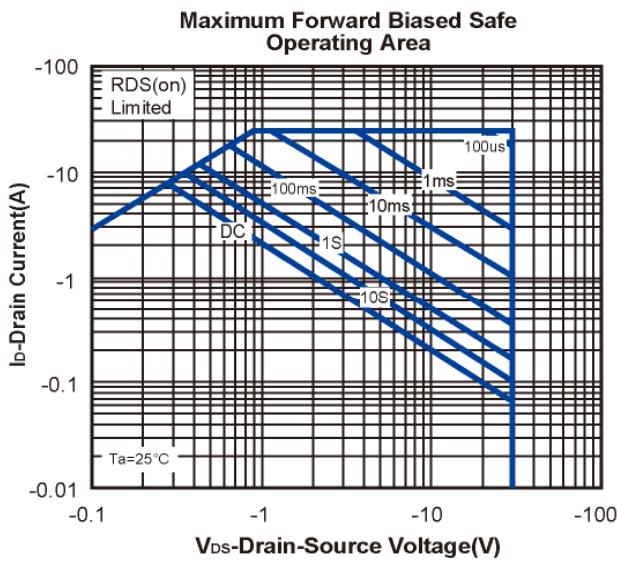
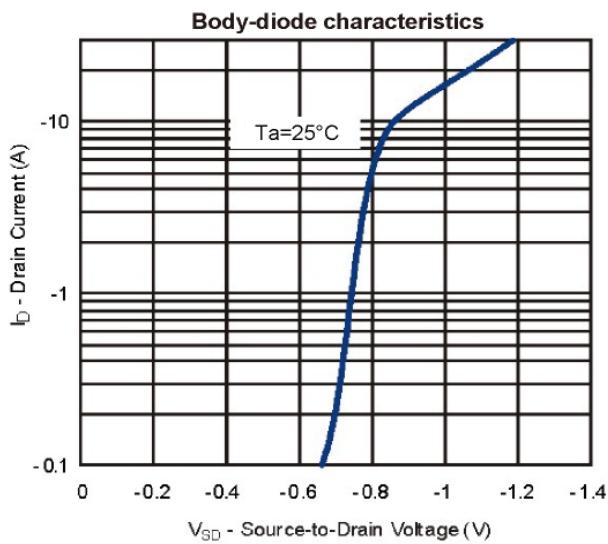
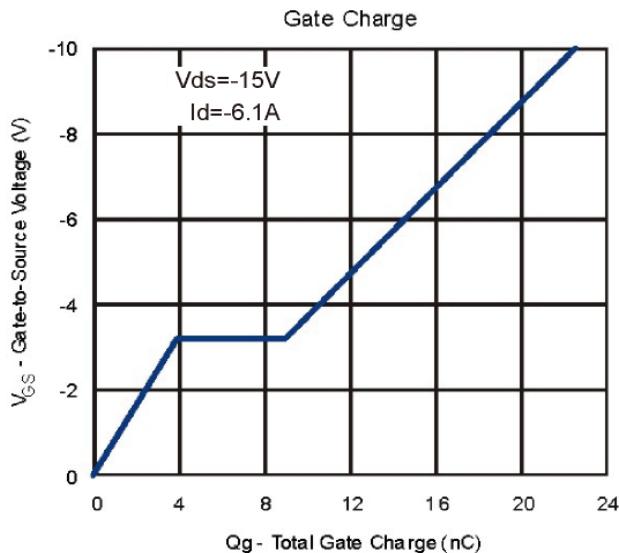
**P-CHANNEL**



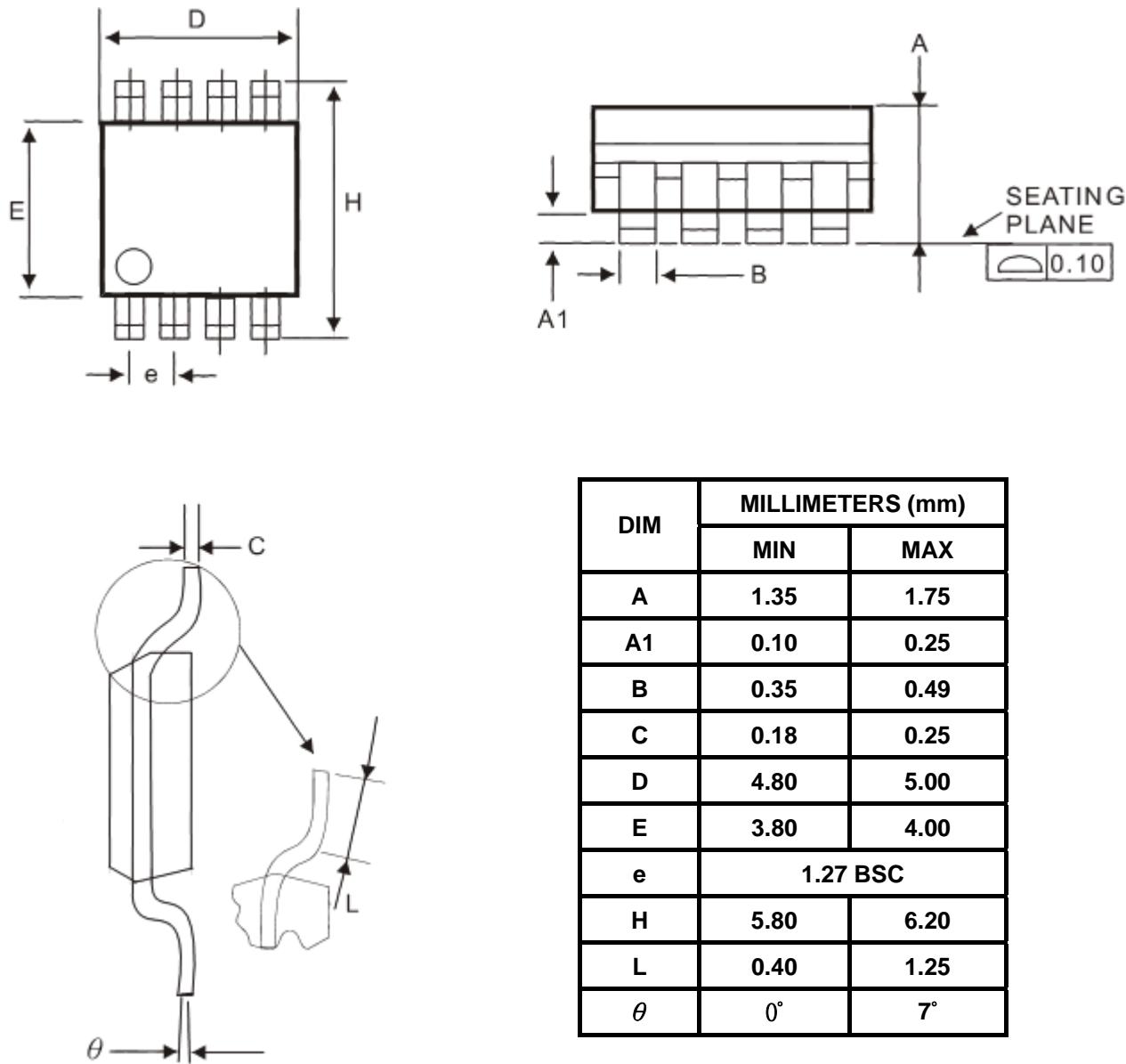
**N and P- Channel 30-V (D-S) MOSFET**

**Typical Characteristics (T<sub>J</sub> =25°C Noted)**

**P-CHANNEL**



## SOP-8 Package Outline



Note: 1. Refer to JEDEC MS-012AA.

2. Dimension "D" does not include mold flash, protrusions or gate burrs . Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per side.